AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously Presented) A wet processing apparatus comprising:

a tank to contain a fluid;

a drain opening in said tank; and

a regulating means with slats and openings disposed in said tank and over said drain opening, wherein one of said slats substantially covers said drain opening to control downward draining rate and downward draining direction of said fluid.

2. (Original) The apparatus according to Claim 1 wherein said drain opening is located on the bottom surface of said tank.

3. (Original) The apparatus according to Claim 1 wherein said fluid comprises de-ionized water.

4. (Original) The apparatus according to Claim 1 further comprising a cassette configured to hold a plurality of integrated circuit wafers in said processing region.

5. (Original) The apparatus according to Claim 1 wherein said regulating means comprises a regulating plate dividing said tank into a processing region and a draining region, and wherein, during draining, fluid in said tank flows from said processing region through said regulating plate, through said draining region, and out said drain opening.

6. (Original) The apparatus according to Claim 5 wherein said regulating plate comprises polyetheretherkefone (PEEK).

7. (Previously presented) The apparatus according to Claim 1 wherein said openings comprise holes.

8. (Original) The apparatus according to Claim 7 further comprising a cassette configured to hold a plurality of integrated circuit wafers in said processing region wherein said integrated circuit wafers are oriented in the same direction as said slats and openings.

9. (Original) The apparatus according to Claim 7 wherein said slats are oriented at an angle of between about 0° and about 45° with respect to the plane of said regulating plate.

10. (Canceled)

11. (Currently amended) The apparatus according to Claim 1 wherein ~~additional~~ at least one of said slats ~~are~~ is angled with respect to the plane of said regulating plate.

12. (Previously Presented) A wet processing apparatus comprising:

a tank;

a drain opening in said tank; and

a regulating plate dividing said tank into a processing region and a draining region, wherein said regulating plate comprises a plurality of slats and openings. wherein one of said slats substantially covers said drain opening, and wherein, during draining, fluid in said tank flows downward from said processing region through said regulating plate, through said draining region, and out said drain opening to control downward draining rate and downward draining direction of said fluid.

13. (Original) The apparatus according to Claim 12 wherein said fluid comprises de-ionized water.

14. (Currently amended) The apparatus according to Claim 12 wherein ~~additional~~ at least one of said slats ~~are~~ is angled with respect to the plane of said regulating plate.

15. (Original) The apparatus according to Claim 12 wherein said regulating plate comprises polyetheretherkefone (PEEK).

16. (Original) The apparatus according to Claim 12 wherein said slats are oriented at an angle of between about 0° and about 45° with respect to the plane of said regulating plate.

17. (Original) The apparatus according to Claim 12 further comprising a cassette configured to hold a plurality of integrated circuit wafers in said processing region wherein said integrated circuit wafers are oriented in the same direction as said slats and openings.

18. (Canceled)

19. (Canceled)

20-28. (Canceled)

29. (Previously Presented) A wet processing apparatus comprising:

a tank;

a drain opening in said tank; and

a regulating plate dividing said tank into a processing region and a draining region, wherein said regulating plate comprises a plurality of slats and openings, wherein one of said slats substantially covers said drain opening, and wherein, during draining, fluid in said tank flows from said processing region through said regulating plate, through said draining region, and out said drain opening to control downward draining rate and downward draining direction of said fluid so as to prevent wafer sticking.